



Silicon Planar Zener Diodes

FEATURES

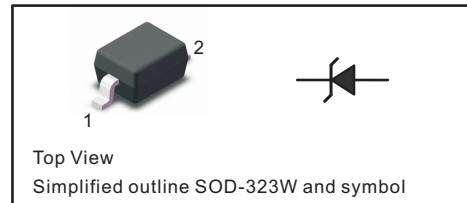
- Total power dissipation: Max. 200mW.
- Wide zener reverse voltage range 2.4V to 43V.
- Ideally suited for automated assembly processes

MECHANICAL DATA

- Case: SOD-323W
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 5.48mg / 0.00019oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings And Characteristics (Ta = 25 °C)

Parameter	Symbol	Value	Unit
Power Dissipation	P_D	200	mW
Forward Voltage at $I_F = 10$ mA	V_F	0.9	V
Typical thermal resistance juncting to ambient	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

Fig.1 Power Derating Curve

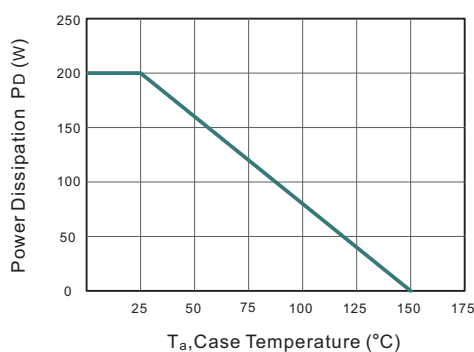
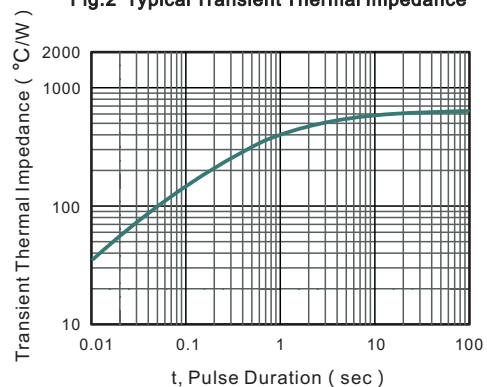


Fig.2 Typical Transient Thermal Impedance





Characteristics at Ta = 25°C

Type	Marking	Zener Voltage Range (NOTE 2)				Maximum Zener Impedance (NOTE 3)			Maximum Reverse Current (NOTE 2)		Typical Temperature Coefficient @I _{ZTC} mV/°C		Test Current I _{ZTC} mA
		V _{ZT} (@ I _{ZT})			I _{ZT}	Z _{ZT} (@ I _{ZT})	Z _{ZK} (@ I _{ZK})	I _{ZK}	I _R	V _R	MIN	MAX	
		Min (V)	Nom (V)	Max (V)	(mA)	(Ω)	mA	μA	V				
BZT52C2V4SW	WX	2.2	2.4	2.6	5	100	600	1	50	1	-3.5	0	5
BZT52C2V7SW	W1	2.5	2.7	2.9	5	100	600	1	20	1	-3.5	0	5
BZT52C3V0SW	W2	2.8	3	3.2	5	95	600	1	10	1	-3.5	0	5
BZT52C3V3SW	W3	3.1	3.3	3.5	5	95	600	1	5	1	-3.5	0	5
BZT52C3V6SW	W4	3.4	3.6	3.8	5	90	600	1	5	1	-3.5	0	5
BZT52C3V9SW	W5	3.7	3.9	4.1	5	90	600	1	3	1	-3.5	0	5
BZT52C4V3SW	W6	4	4.3	4.6	5	90	600	1	3	1	-3.5	0	5
BZT52C4V7SW	W7	4.4	4.7	5	5	80	500	1	3	2	-3.5	0.2	5
BZT52C5V1SW	W8	4.8	5.1	5.4	5	60	480	1	2	2	-2.7	1.2	5
BZT52C5V6SW	W9	5.2	5.6	6	5	40	400	1	1	2	-2	2.5	5
BZT52C6V2SW	WA	5.8	6.2	6.6	5	10	150	1	3	4	0.4	3.7	5
BZT52C6V8SW	WB	6.4	6.8	7.2	5	15	80	1	2	4	1.2	4.5	5
BZT52C7V5SW	WC	7	7.5	7.9	5	15	80	1	1	5	2.5	5.3	5
BZT52C8V2SW	WD	7.7	8.2	8.7	5	15	80	1	0.7	5	3.2	6.2	5
BZT52C9V1SW	WE	8.5	9.1	9.6	5	15	100	1	0.5	6	3.8	7	5
BZT52C10SW	WF	9.4	10	10.6	5	20	150	1	0.2	7	4.5	8	5
BZT52C11SW	WG	10.4	11	11.6	5	20	150	1	0.1	8	5.4	9	5
BZT52C12SW	WH	11.4	12	12.7	5	25	150	1	0.1	8	6	10	5
BZT52C13SW	WI	12.4	13	14.1	5	30	170	1	0.1	8	7	11	5
BZT52C15SW	WJ	13.8	15	15.6	5	30	200	1	0.1	10.5	9.2	13	5
BZT52C16SW	WK	15.3	16	17.1	5	40	200	1	0.1	11.2	10.4	14	5
BZT52C18SW	WL	16.8	18	19.1	5	45	225	1	0.1	12.6	12.4	16	5
BZT52C20SW	WM	18.8	20	21.2	5	55	225	1	0.1	14	14.4	18	5
BZT52C22SW	WN	20.8	22	23.3	5	55	250	1	0.1	15.4	16.4	20	5
BZT52C24SW	WO	22.8	24	25.6	5	70	250	1	0.1	16.8	18.4	22	5
BZT52C27SW	WP	25.1	27	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3	2
BZT52C30SW	WQ	28	30	32	2	80	300	0.5	0.1	21	24.4	29.4	2
BZT52C33SW	WR	31	33	35	2	80	325	0.5	0.1	23.1	27.4	33.4	2
BZT52C36SW	WS	34	36	38	2	90	350	0.5	0.1	25.2	30.4	37.4	2
BZT52C39SW	WT	37	39	41	2	130	350	0.5	0.1	27.3	33.4	41.2	2
BZT52C43SW	WU	40	43	46	2	100	700	1	0.1	32	10	12	5

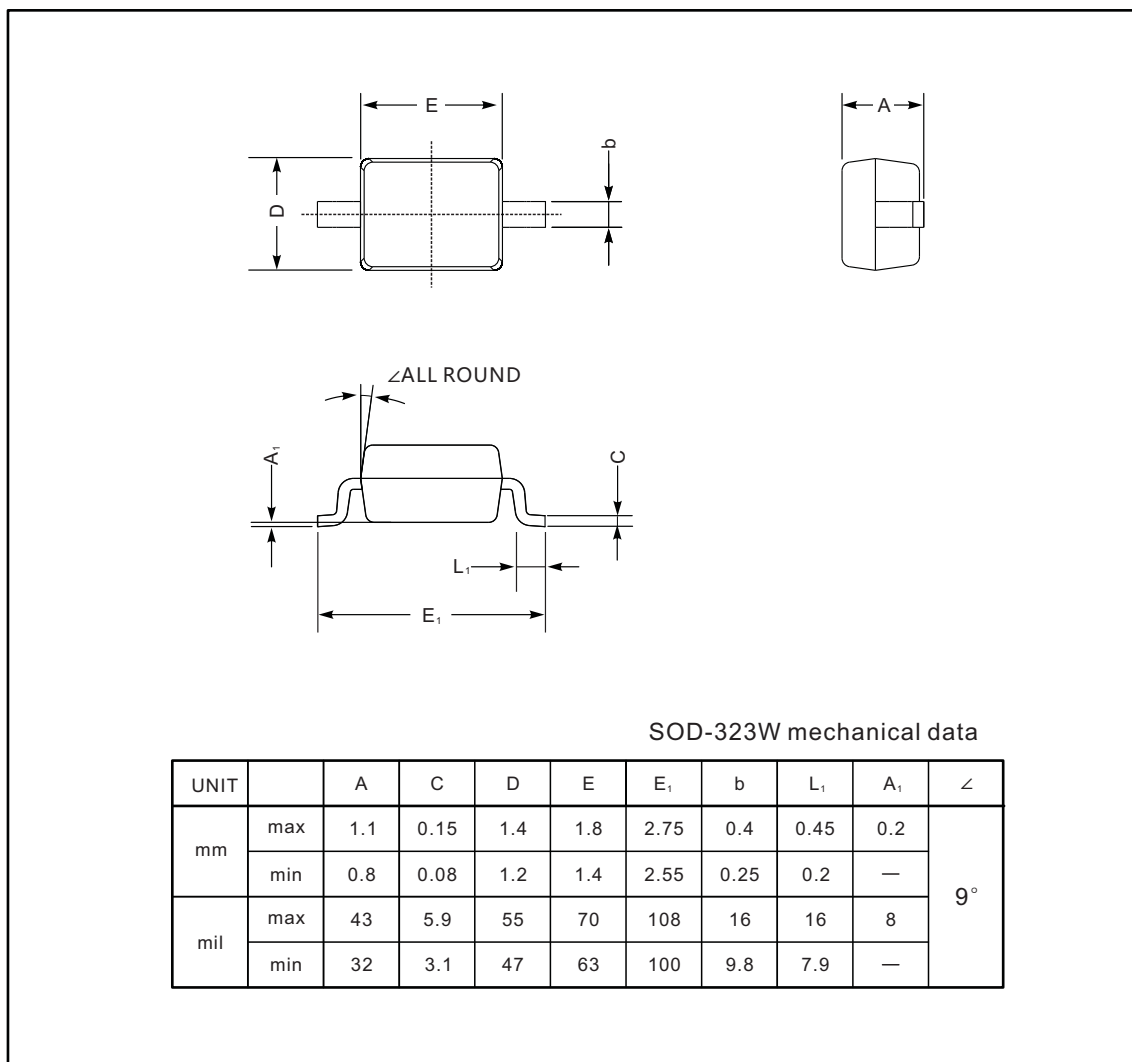
NOTE: 1. Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm².
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323W



The recommended mounting pad size

